Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
HP D3000 Storage Enclosure
D3600/D3700

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		

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Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

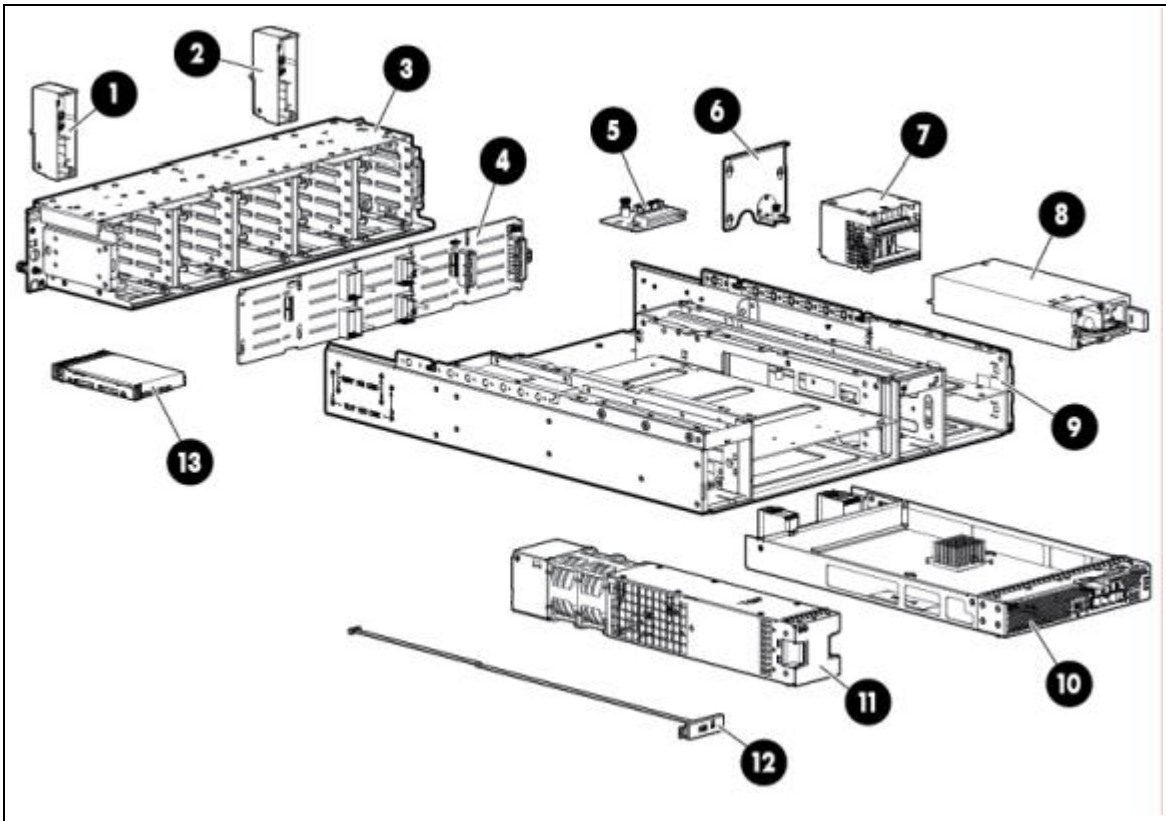
Tool Description	Tool Size (if applicable)
Torx	T-15
Torx	T-10
Flat blade screw driver	

3.0 Product Disassembly Process

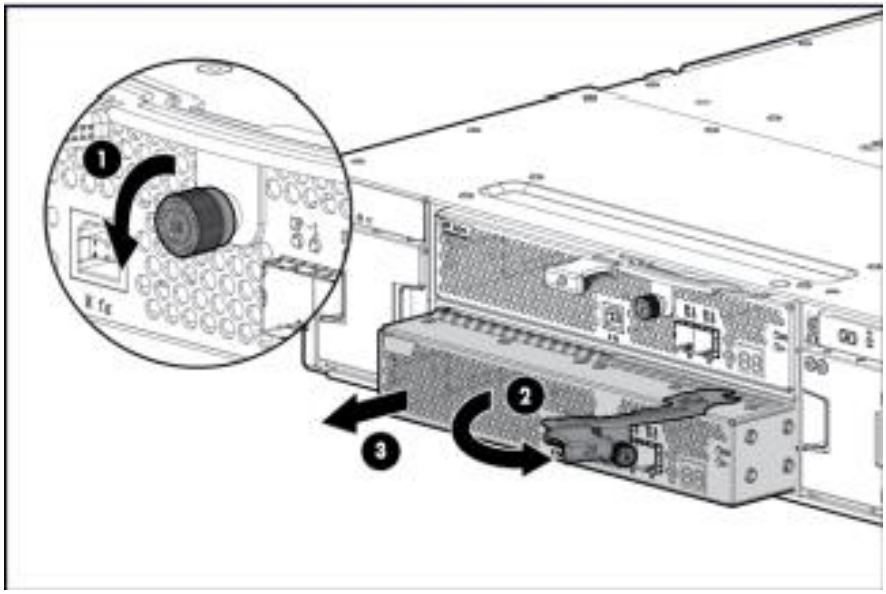
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove both IO Module trays from the rear of the unit (loosen thumbscrew by hand or with T15) (Item 10)
2. Remove 3 screws securing air dam wall from top of PCB on both IO module trays using T10 driver
3. Remove IO module PCB from tray - T15 driver required to remove 4 screws
4. Remove Power supplies from chassis (Item 8)
5. Remove both fan modules from rear of chassis (item 11)
6. On fan module, use T10 driver to remove two screws from front of module near fan controller PCB
7. Use T10 driver to remove PCB from fan sheet metal tray
8. Use T10 driver on 4 guide screws to remove fans from module
9. Remove black plastic cover from UID button on rear of chassis (Item 12)
10. Unlatch and remove top cover from chassis
11. Unlatch UID power flex cable from backplane (Item 12)
12. Unlatch/remove all remaining cables from interior of chassis
13. Using flat blade screw driver or equivalent, break adhesive bond of UID flex front surface of cable from rear of chassis
14. Loosen captive screw on air dam wall in front of Power Disribution Board Module (Item 6)
15. Remove top T10 screw and loosen captive screw 1 from Power Distribution Board Module, then slide out of chassis (Item 7)
16. Use T15 driver on captive fastener of fan interposer board interior to chassis behind the backplane to loosen and then slide to remove - repeat for second PCB (Item 5)
17. Remove set of 8 black screws (T10 driver) securing HDD drive cage into chassis (Item 3)
18. Slide HDD cage up and out of chassis
19. Remove 2 screws securing backplane with T15 driver (Item 4)
20. Slide backplane up and out of cage (Item 4)
21. Remove right ear from HDD cage sheet metal ear bracket using T10 driver (item 1)
22. Using flat blade screw driver, remove the two standoffs securing the PCB into the plastic ear
23. Remove left ear from HDD cage sheet metal ear bracket using T10 driver (Item 2)
24. Using flat head thin screw driver, unlatch DS cable from inside of ear

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



Step 1:



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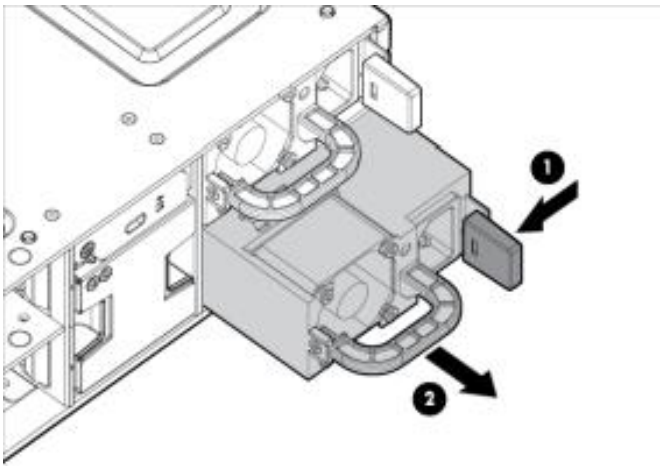
Step 4:



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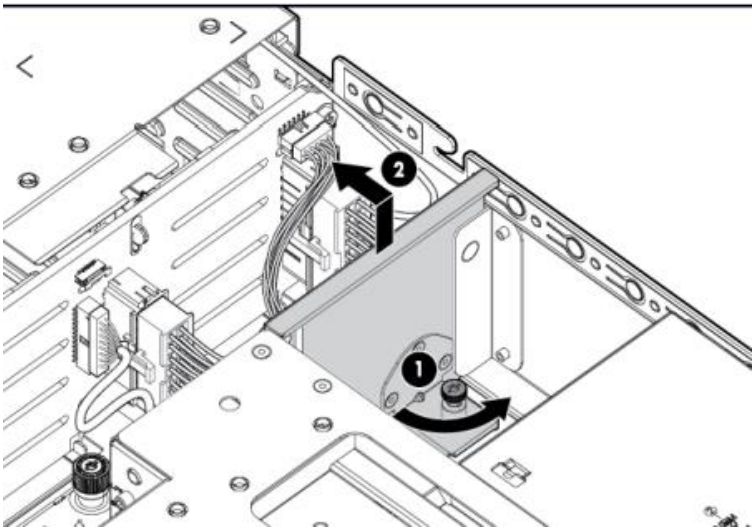

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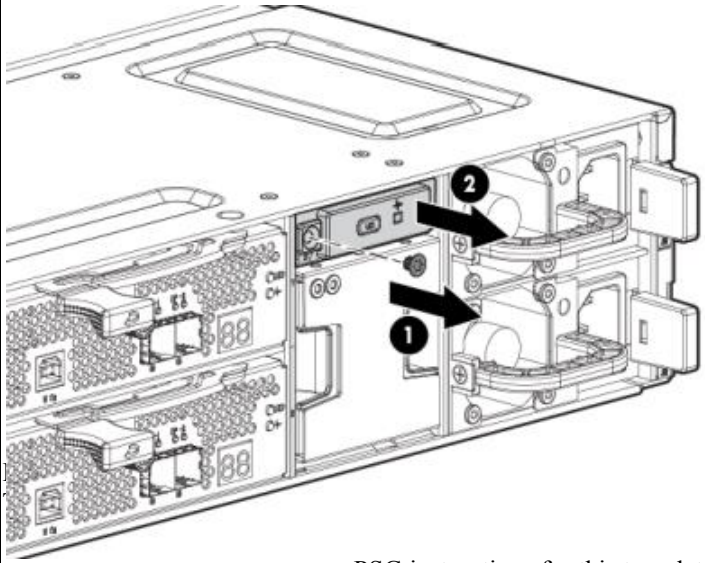

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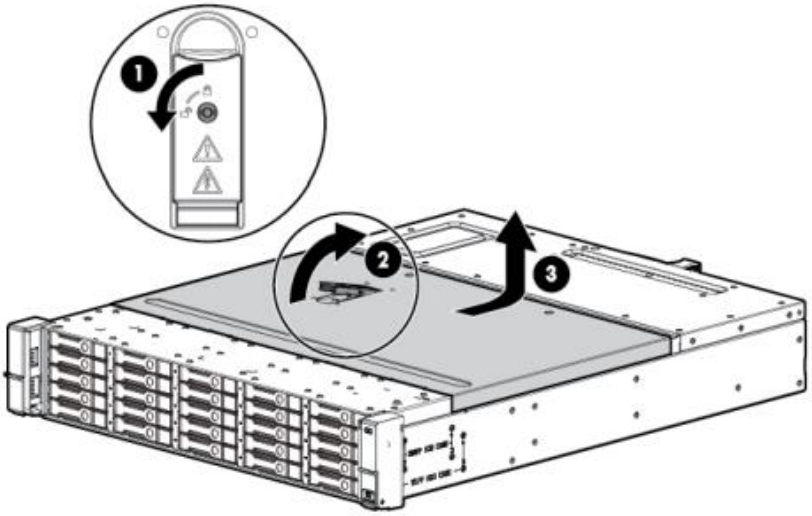
Step 10:



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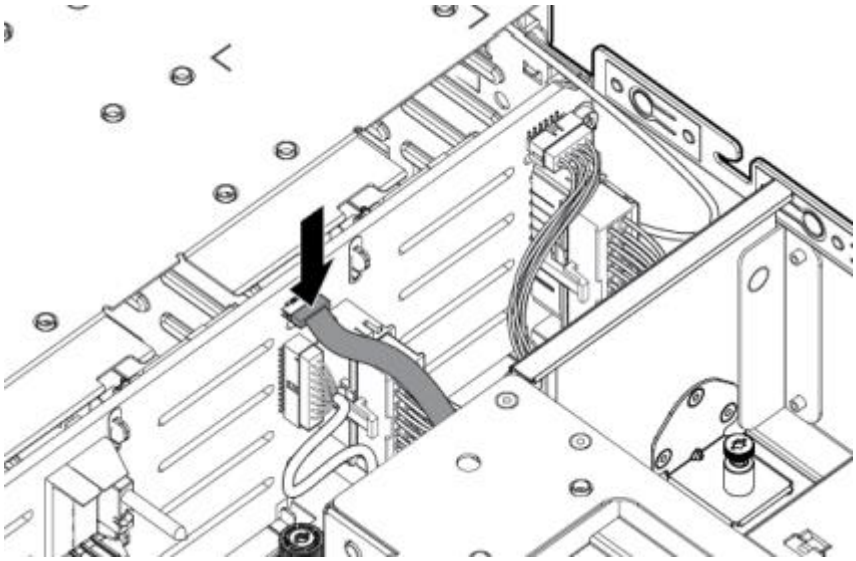

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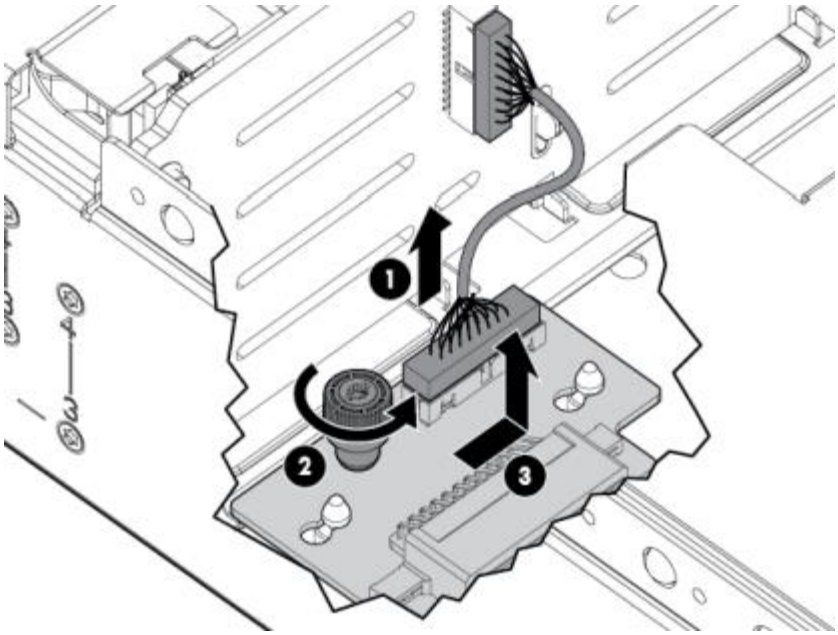
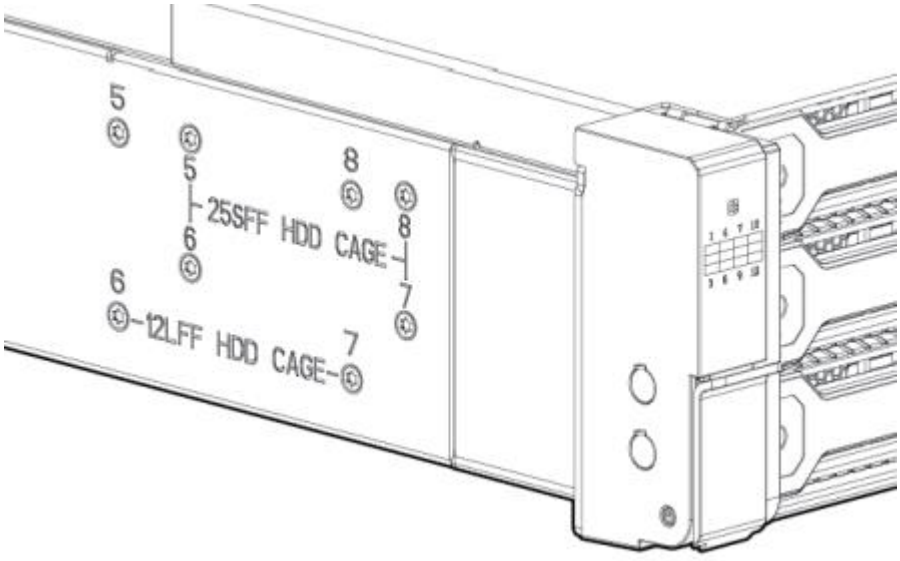


Step 17:



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